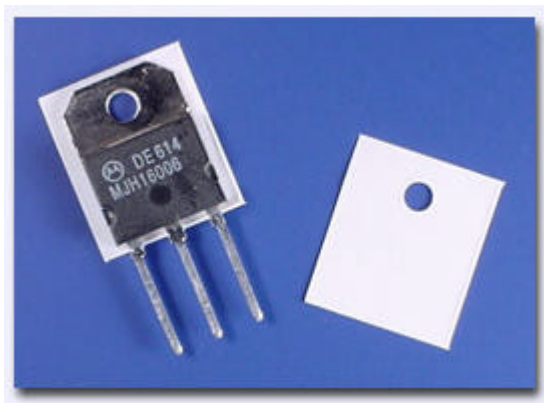


**Thermaphase on Aluminum Foil 71°C
Thermafoil "Tacky2"**

(Electrically and Thermally Conductive Thermal Interface Material)



Advantages:

- ?? Thermal Resistance 0.06°C/W/in² at 15psi
- ?? Naturally tacky on both sides for easy application to heat sink
- ?? Manufacturing Friendly - easy to handle
- ?? Thixotropic and won't flow from gaps
- ?? Excellent heat spreading characteristic
- ?? Precision metered coating 0.5 to 6.0 mils thick
- ?? Available with different compound thickness on each side of foil
- ?? Thermoplastic reversible adhesive bond

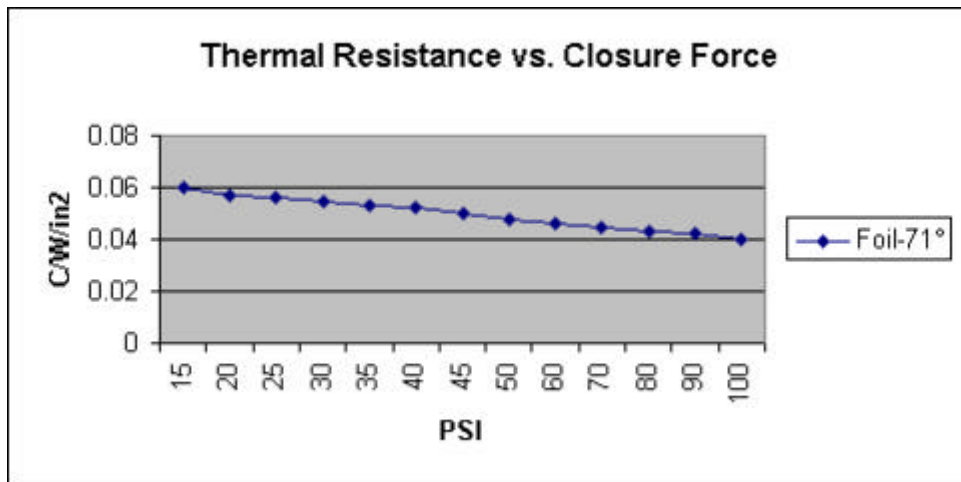
Description:

"Tacky2"- 71°C Thermaphase compound is pre-coated onto a 2-mil Aluminum substrate. This material is slightly adhesive at room temperature. It can be temporarily adhered to heat sink surfaces by simply pressing it firmly onto the heat sink. When the temperature of this material exceeds the reflow temperature, the compound reflows and fills all of the pores of both electronic component and heat sink to form a very low thermal resistance interface. The material requires only 10psi of closure force to flow when in the molten state and creates a very thin thermal interface. This material is thermoplastic. It can be reflowed and solidified innumerable times. After initial reflow and when re-solidified by cooling to a temperature below the phase change temperature, this material has an adhesive strength of 25psi. Simply heating above the phase change temperature for component removal can break the adhesive bond. This material can replace thermally conductive epoxies in most applications. It is not a thermosetting material like epoxy. It can operate either in the solid or reflowed state.

Typical Characteristics:

Thermal Characteristics	Units	Aluminum Foil
Overall Thermal Resistance at 15psi. See graph of Thermal Resistance vs Closure Force (See test procedure)	°C/W/in ²	0.06
Thermal Conductivity of Aluminum Substrate	W/m ² .K	221

Specific Heat of Thermaphase	Cp	1801.6
Phase Change Temperature	°C	71
Use Temperature	°C	-60 to +200
Mechanical Characteristics	Units	Aluminum Foil
Substrate Material	----	1100 Aluminum
Substrate Thickness	inches	0.002
Coating thickness	mils	0.5 to 6.0
Viscosity (Thermaphase compound) at 150°C	Poise	>100
Density of Thermaphase Compound	g/cc	2.1



Thermal Resistance versus Closure Force

Options:

On special order this product is available on other types of metal foils.

How to Use:

The applications of Thermafoil 71°C "Tacky2" are the same as for Thermafoil 52°C. It is easy to apply to a heat sink by simply pressing the Thermafoil "Tacky2" part onto the heat sink at room temperature. It does not require heat to temporarily adhere the pad to the heat sink. Use "Tacky2" in any application that requires a low thermal resistance path between electronic component and heat sink and the convenience of room temperature application of the interface to the heat sink surface. Thermafoil "Tacky2" is thermoplastic. When reflowed under low closure force it flows into all surface imperfections of component and heat sink. When re-solidified it adheres the component to the heat sink. For component removal, simply reheat above the phase change temperature.

Product Availability:

Standard Sheets: 12"x12"

Standard Rolls: 12"x500 ft.

Standard die-cut parts: Pads for all standard case sizes are available.

